



Gold Nanoparticles: Properties and Applications

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Message from the Guest Editor

Dear Colleagues,

Nanoparticle-based materials are a revolutionary scientific and engineering venture that will invariably impact the existing electric, optoelectronic, magnetic, biosensing, thermoelectric, mechanic, ceramic, and semiconductor devices. Nanoparticles can be regarded as a hybrid between a small molecule and a bulk material. A size- and shape-dependent material on the nanoscale demonstrates considerable variation on the above properties. Gold nanoparticles (Au NPs), only one among the wide variety of core materials available, coupled with tunable surface properties in the form of an inorganic or inorganic–organic hybrid, have been reported as an excellent platform for a broad range of next-generation applications. This Special Issue aims at publishing research on Au NP-based materials in the form of a pristine, molecular self-assembly, hybrid, or conjugate. It is my pleasure to invite you to submit original research manuscripts within the scope of this Special Issue. Short communication and state-of-the-art reviews will also be greatly appreciated.

Prof. Fu-Hsiang Ko
Guest Editor





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Message from the Editor-in-Chief

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